

### Dual N-channel Power MOSFET 20V, 11.9mohm, 9.7A

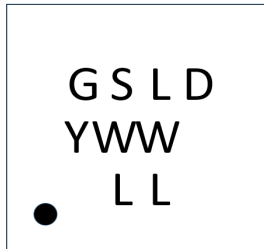
#### Product Summary

VSSS	VGSS	RSS(ON) TYP/MAX	IS MAX
20V	± 8V	9.4/11.9mΩ@VGS=4.5V 10.0/12.9mΩ@VGS=3.8V 11.1/15.8mΩ@VGS=3.1V 13.4/22.6mΩ@VGS=2.5V	9.7A

#### Features

- ❖ CSP (Chip Size Package)
- ❖ Halogen-Free / RoHS Compliant
- ❖ 2.5V Drive Low Source-Source On-State Resistance
- ❖ Gate Resistor Installed Common-Drain Type MOSFET
- ❖ ESD Protection Diode Installed (Gate-Source)

#### Package & Internal Circuit



GS: Gostone  
L: Marking Device Code (fixed)  
D: Factory Code  
Y: Year Code  
W: Week Code  
L: LOT Code  
●Pin#1 Identifier

#### Ordering Information

Tape & Reel Embossed Type: 8,000pcs / reel

#### Absolute Maximum Rating (Ta=25°C)

Parameter	Symbol	Rating	Unit
Source to Source Voltage	VSS	20.0	V
Gate to Source Voltage	VGS	±8	V
Source Current	DC	IS1 *1	5.6 A
	DC	IS2 *2	9.7 A
	Pulse	ISP *2*3	39 A
Total Dissipation	DC	PD1 *1	0.4 W
	DC	PD2 *2	1.18 W
Junction Temperature	Tj	150	°C
Storage Temperature	Tstg	-55 to +150	°C

#### Thermal Characteristic (Ta=25°C)

Parameter	Symbol	Rating	Unit
Thermal Resistance	Rth *1	311	°C/W
	Rth *2	106	°C/W

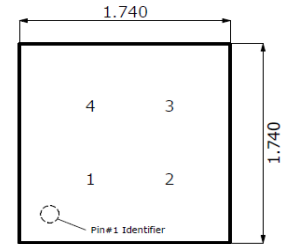
Note \*1 Mounted on FR4 board (25.4mm x 25.4mm x t1.0mm)  
with minimum copper pad (44.6mm<sup>2</sup>, 36μm thickness copper)

Note \*2 Mounted on FR4 board (25.4mm x 25.4mm x t1.0mm)  
with maximum copper pad (617.5mm<sup>2</sup>, 36μm thickness copper)

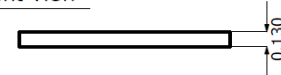
Note \*3 t=10μs, duty cycle ≤ 1%

#### Pin Assignment

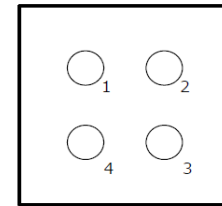
Top View (Unit: mm)



Front View

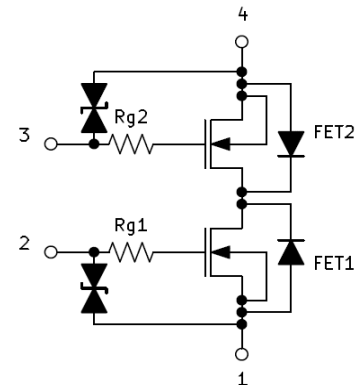


Bottom View



FET1 1: Source1, 2: Gate1  
FET2 4: Source2, 3: Gate2

#### Equivalent Circuit



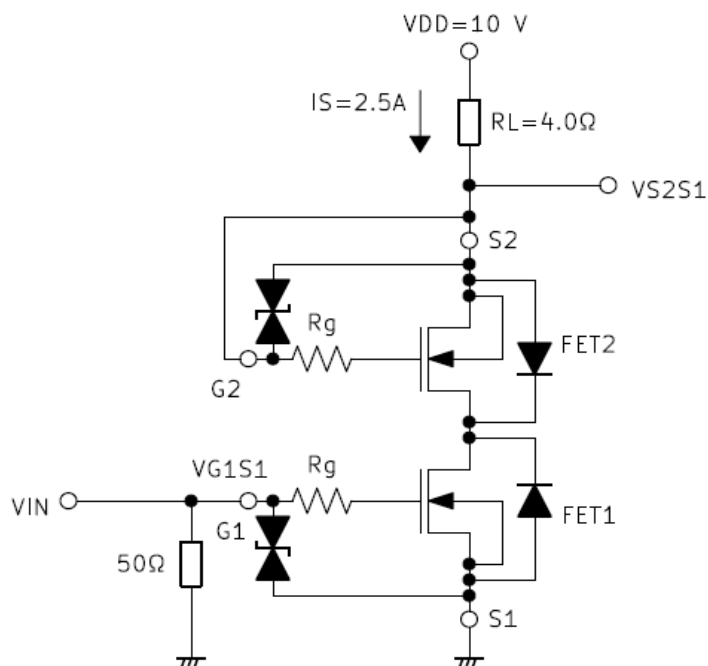
**Electrical characteristics (Ta=25°C ± 3°C)**

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Source-Source Breakdown Voltage	VSSS	IS=1mA, VGS=0V	20.0			V
Zero Gate Voltage Source Current	ISSS	VSS=20V, VGS=0V			1.0	μA
Gate-Source Leakage Current	IGSS1	VGS=±8V, VSS=0V			±10	μA
	IGSS2	VGS=±5V, VSS=0V			±1.0	
Gate-Source Threshold Voltage	Vth	VSS=10.0V, IS=1.0mA	0.35	0.9	1.4	V
Source-Source On-State Resistance	RSS(on)1	IS=2.5A, VGS=4.5V	7.0	9.4	11.9	mΩ
	RSS(on)2	IS=2.5A, VGS=3.8V	7.3	10.0	12.9	
	RSS(on)3	IS=2.5A, VGS=3.1V	8.1	11.1	15.8	
	RSS(on)4	IS=2.5A, VGS=2.5V	8.6	13.4	22.6	
Body Diode Forward Voltage	VF(S-S)	IF=2.5A, VGS=0V		0.7	1.2	V
Input Capacitance *1	Ciss			2,539		pF
Output Capacitance *1	Coss	VSS=10V, VGS=0V, f=1kHz		210		
Reverse Transfer Capacitance *1	Crss			178		
Turn-On Delay Time *1 *2	td(on)	VDD=10V, VGS=0 to 4.0V,		0.4		μs
Rise Time *1 *2	tr	IS=2.5A		0.6		
Turn-Off Delay Time *1 *2	td(off)	VDD=10V, VGS=4.0 to 0V,		2.9		μs
Fall Time *1 *2	tf	IS=2.5A		1.3		
Total Gate Charge *1	Qg	VDD=10V, VGS=0 to 4.0V,		22.8		nC
Gate-Source Charge *1	Qgs	IS=2.5A		4.0		
Gate-Drain Charge *1	Qgd			6.3		
Gate Resistance *1	Rg	f=1MHz		900		Ω

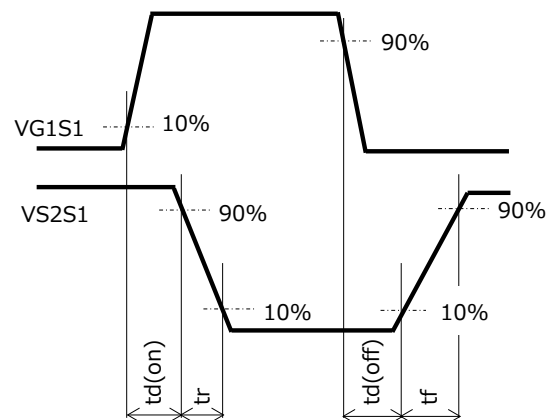
Note \*1 Guaranteed by Design

Note \*2 Measurement Circuit for Switching Characteristics

- FET1 Measurement Circuit for Switching Characteristics td(on), tr, td(off), tf  
(FET2: Gate-Source Short)

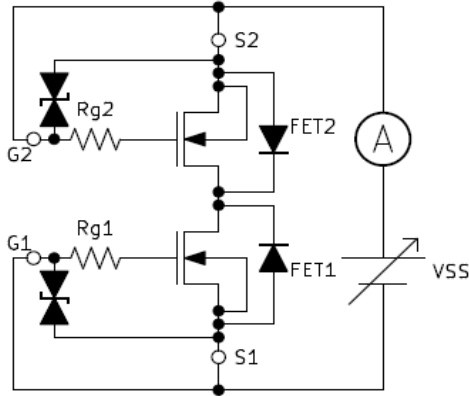


(Definition of Switching Measurement Detection)

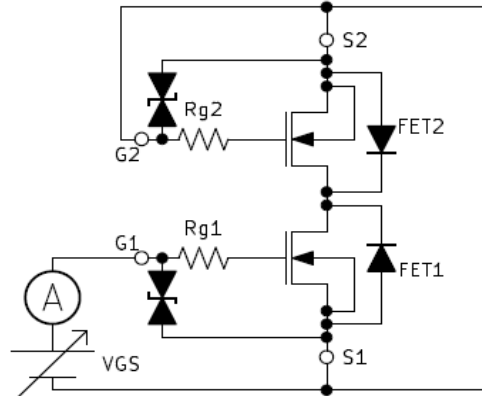


**Test circuits for FET1**

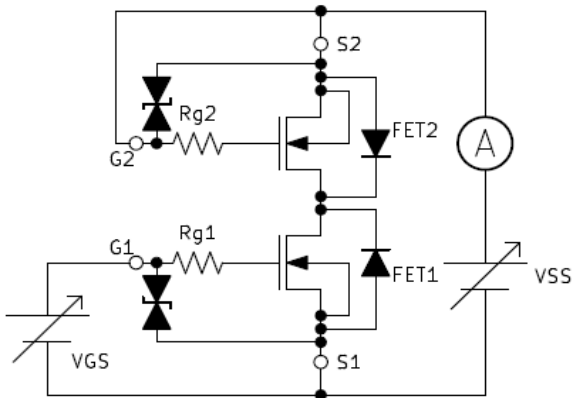
**Test Circuit 1**  
VSSS/ISSS



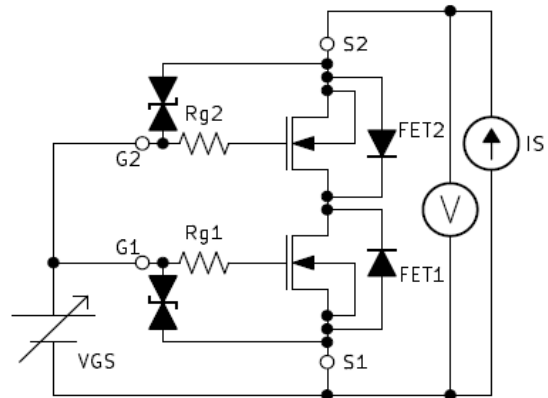
**Test Circuit 2**  
IGSS1/2



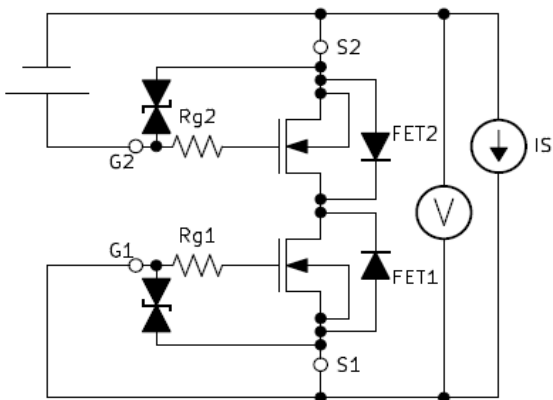
**Test Circuit 3**  
Vth



**Test Circuit 4**  
RSS(on)



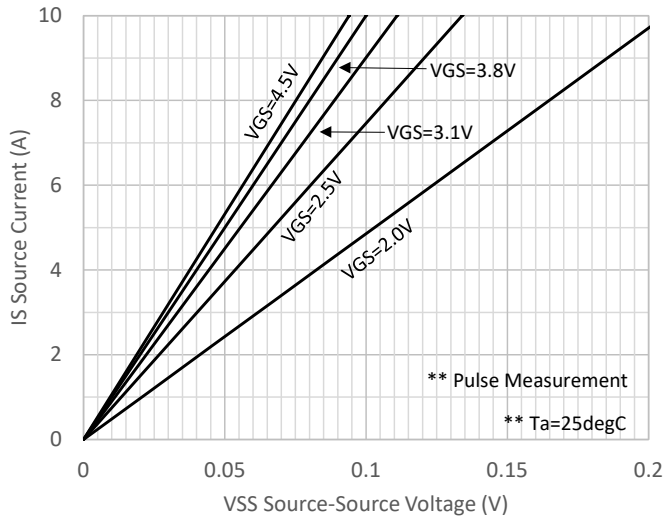
**Test Circuit 5**  
VF(S-S)



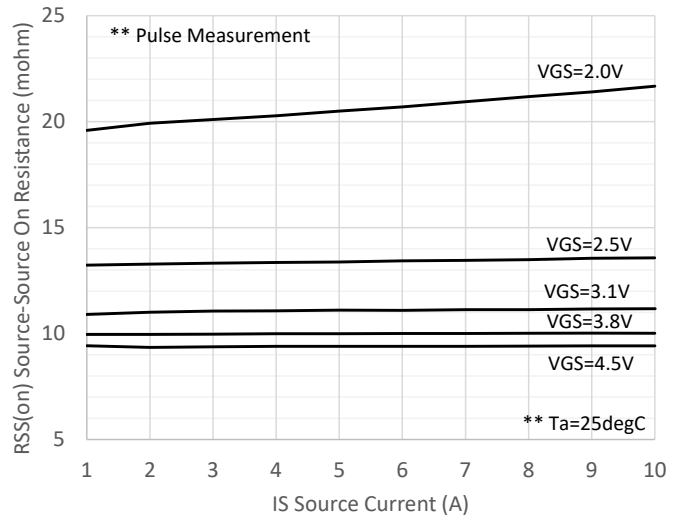


Technical data

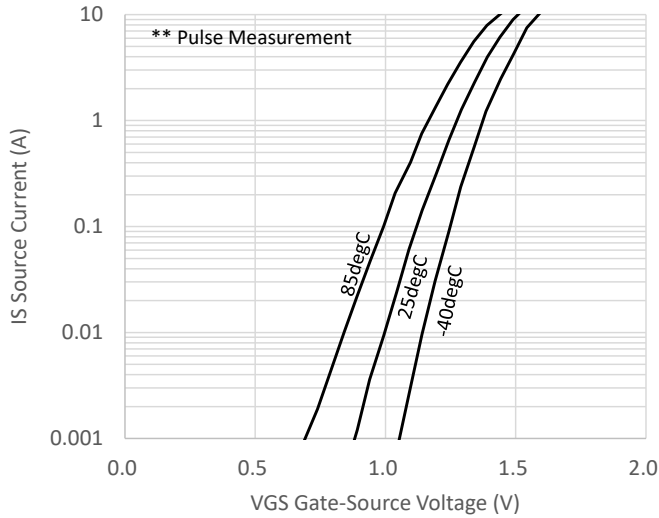
IS to VSS



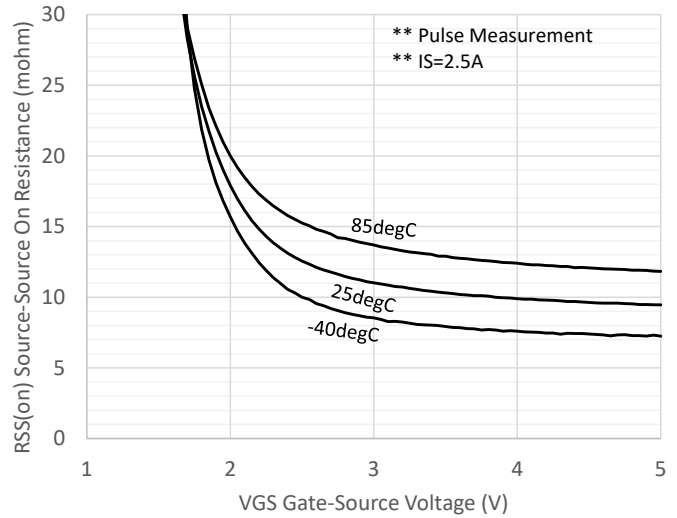
RSS(on) to IS



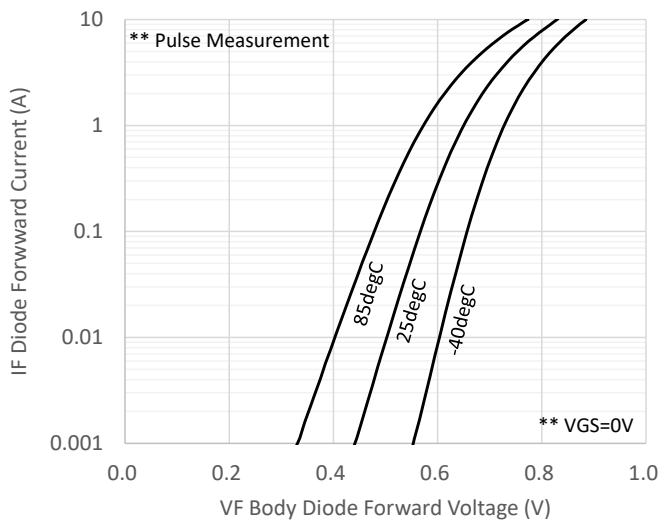
IS to VGS



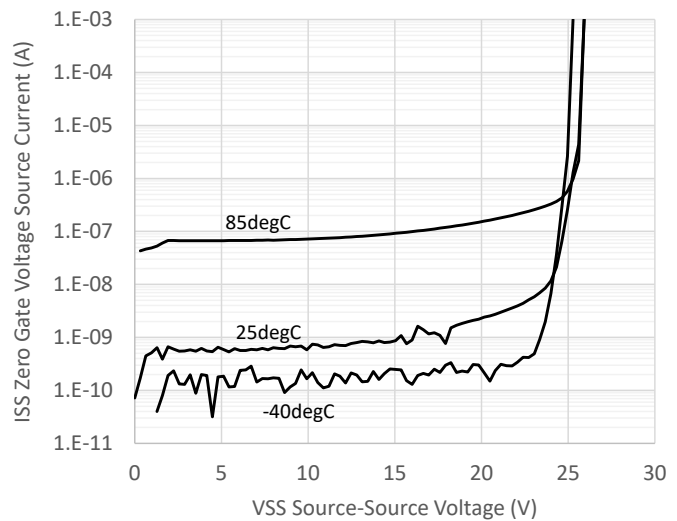
RSS(on) to VGS



IF to VF

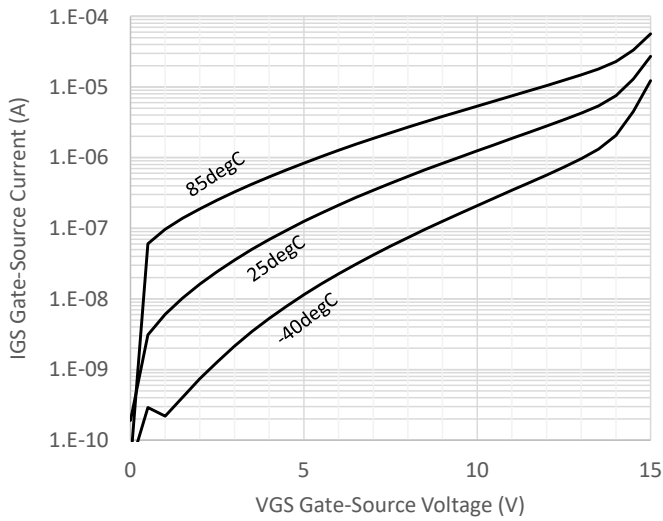


ISS to VSS

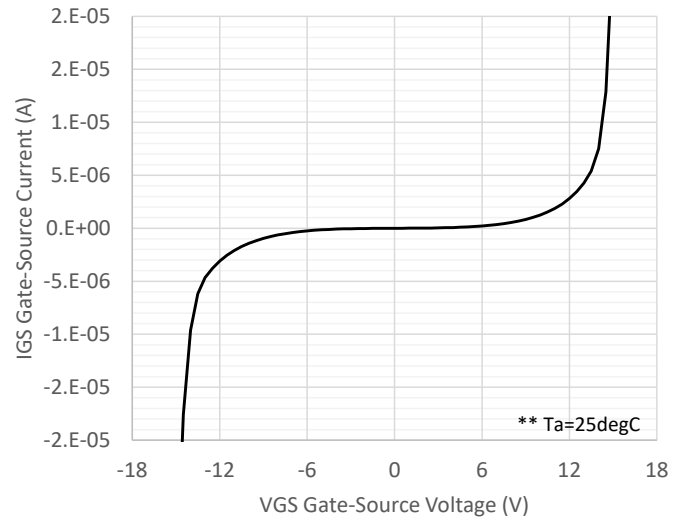


## Technical data

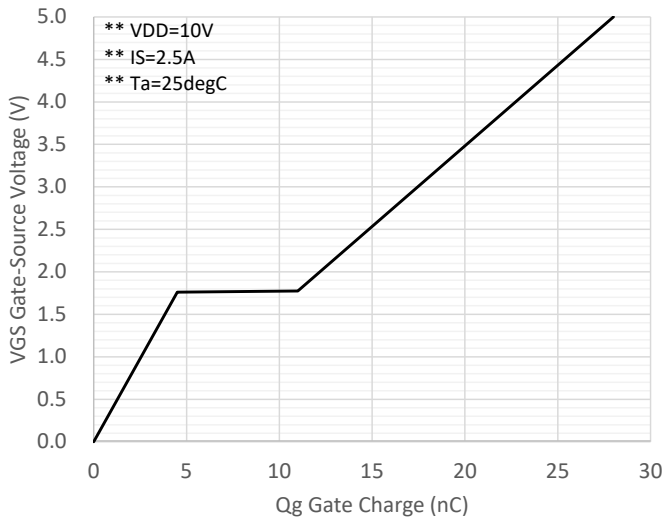
IGS to VGS



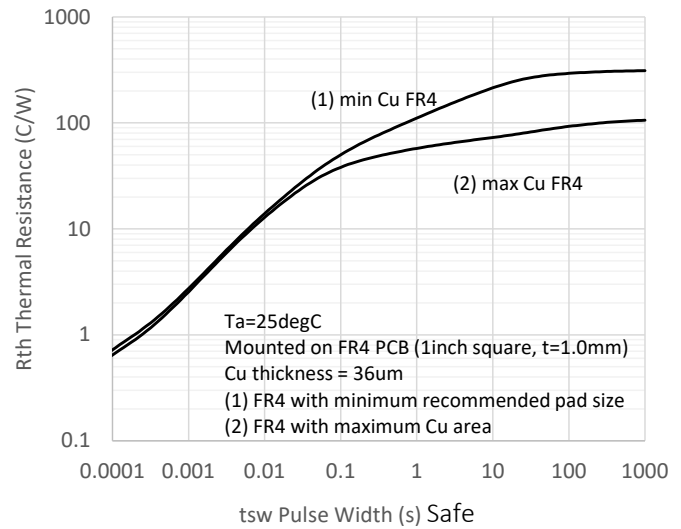
IGS to VGS



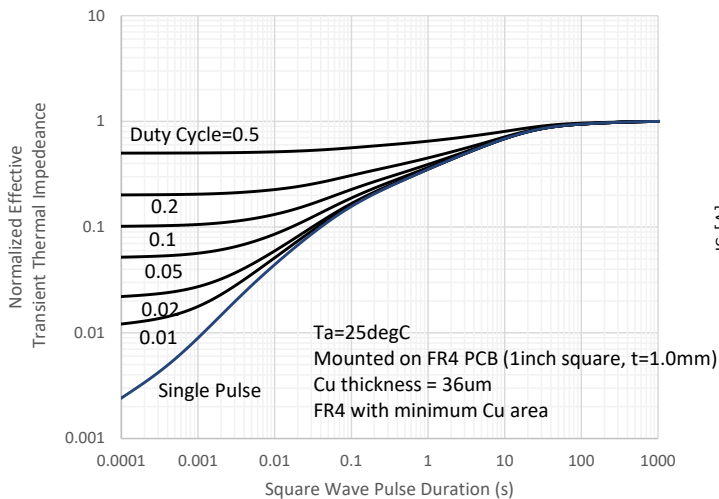
Dynamic Input / Output Characteristics



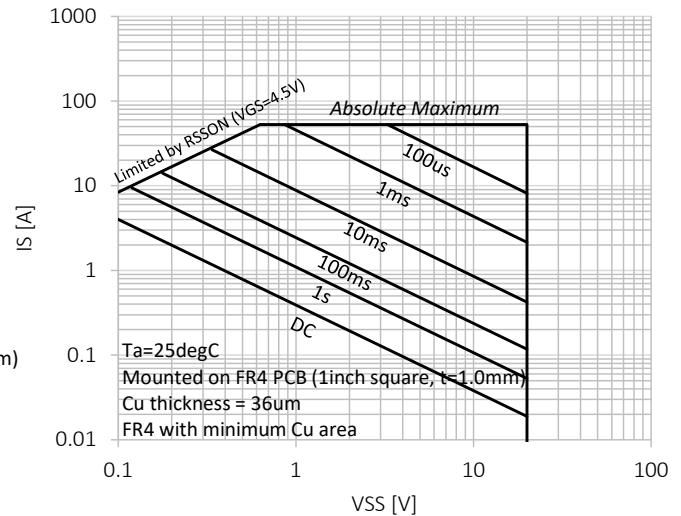
Rth to tsw



Thermal Response

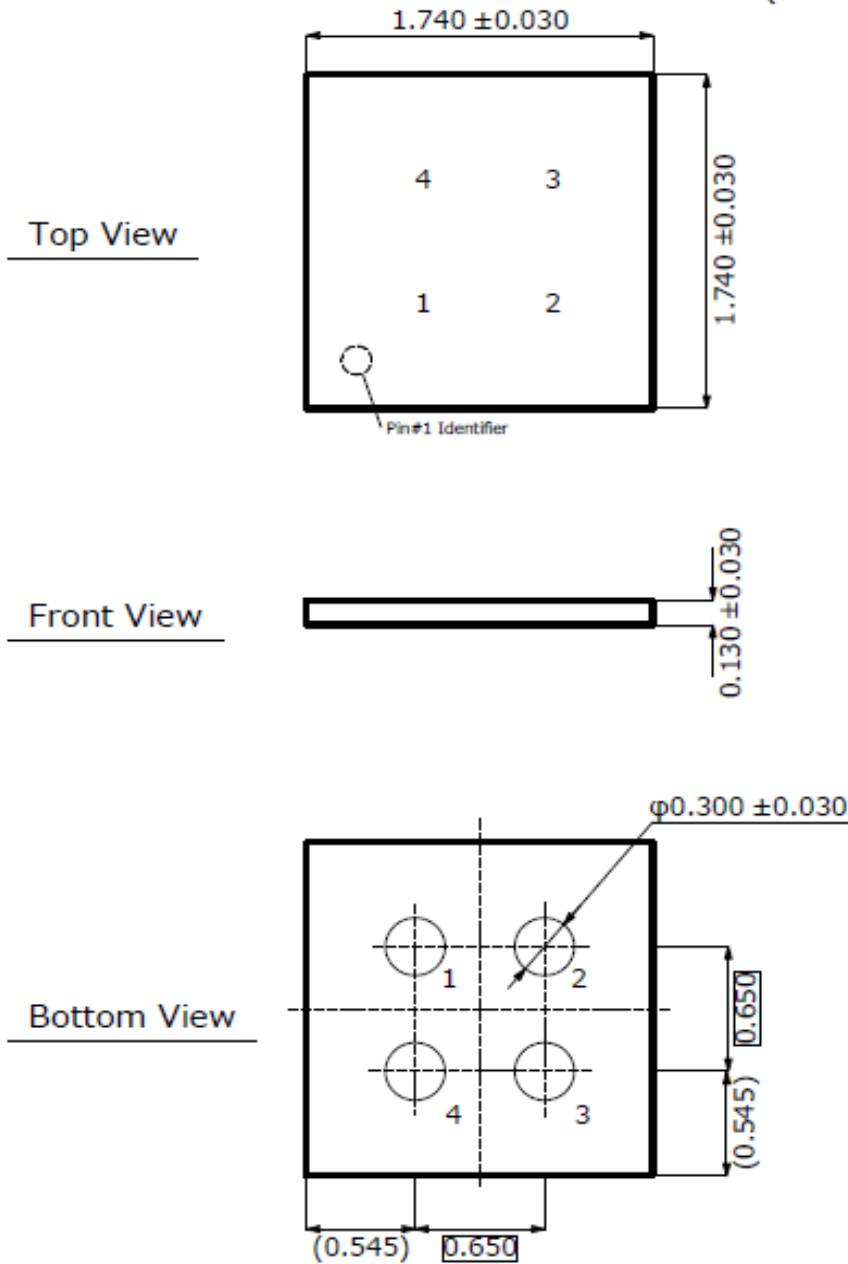


Safe Operating Area

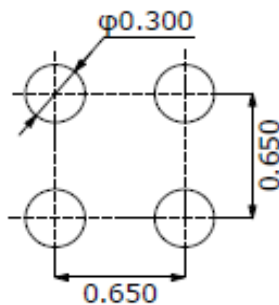


**Package outline dimensions**

(Unit: mm)



(Reference) Board Land and Stencil Mask Pattern



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